

# Assessing BBICS Efficiency in Monitoring Triple-Well Logic and Picosecond LFI

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**Bulk-Built in Current Sensor (BBICS) as a LFI countermeasure [1]**

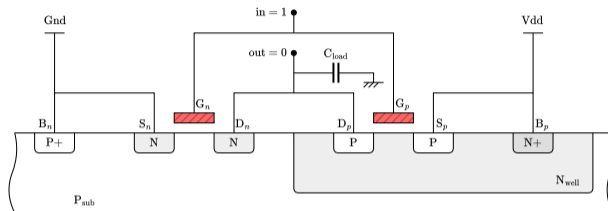
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- › BBICS Principle
- › BBICS Experimental State-of-the-Art
- › Experimental Methodology & Setup
- › Experimental Assessment
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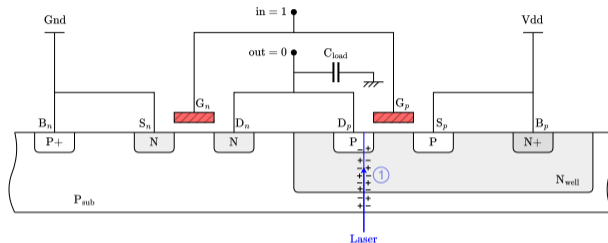
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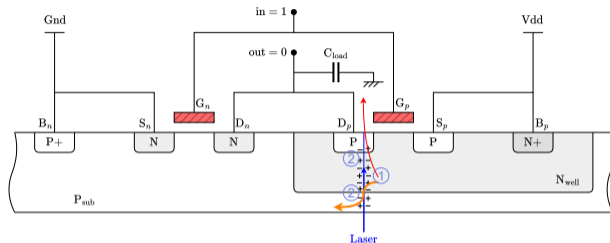


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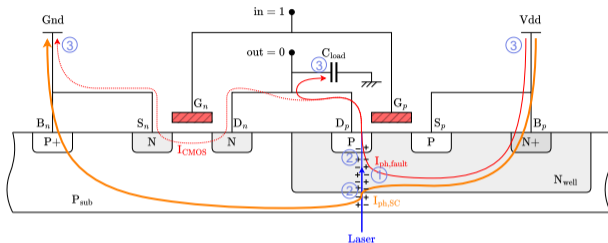
## 1. Charge Generation (excess charge carriers due to photon absorption)

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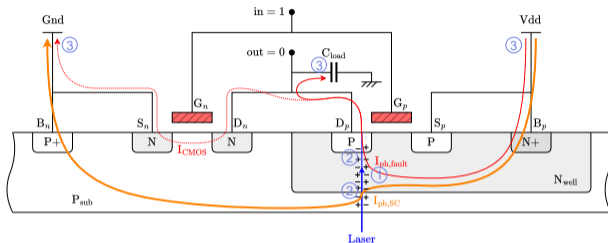
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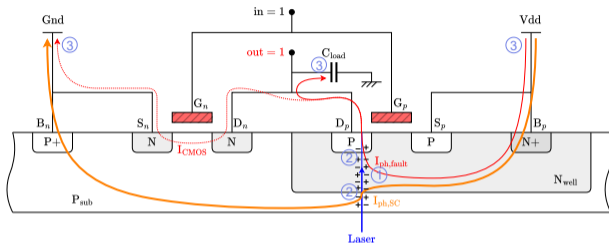
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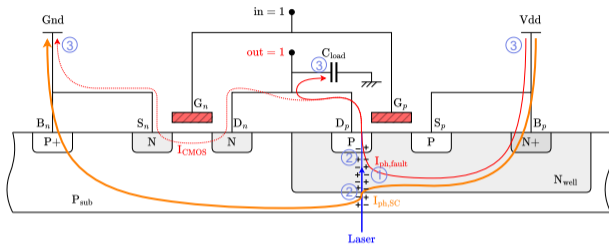
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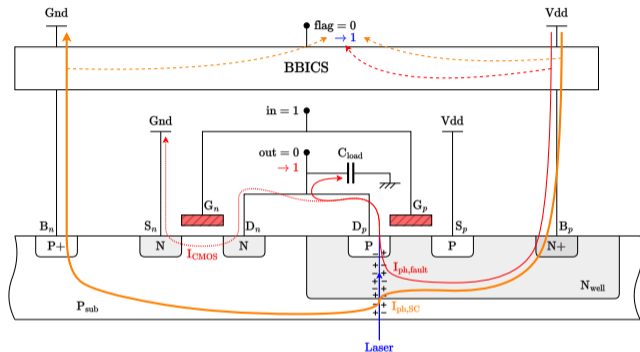


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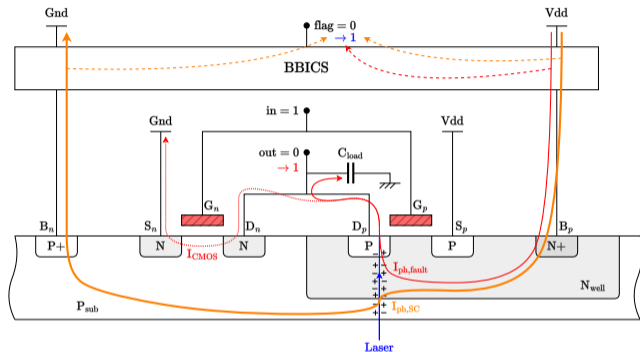
Charges are captured by bulks biasing contacts ( $B_n$  and  $B_p$ )

# MONITORING A DUAL-WELL INVERTER WITH A BBICS



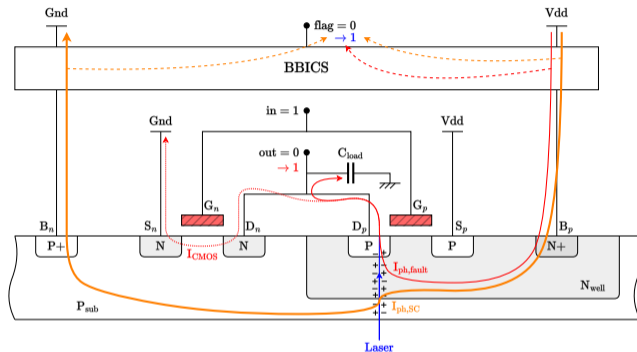
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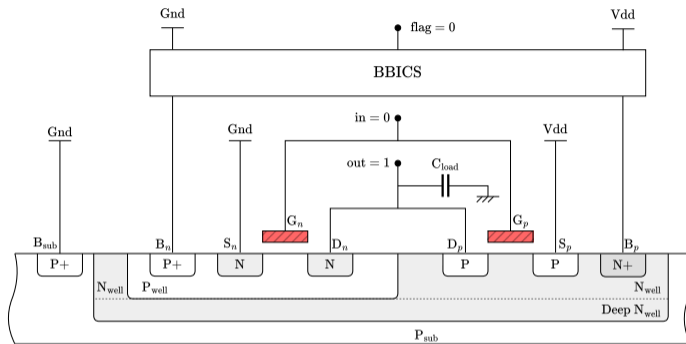
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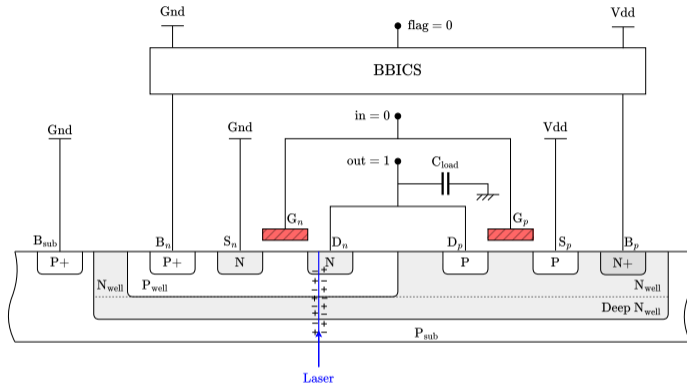


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Provides biasing to bulk to ensure photocurrent capture  
 $I_{ph,SC}$  participates in the detection process

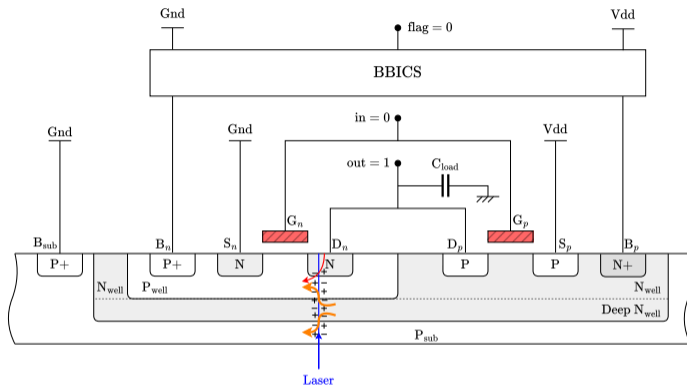
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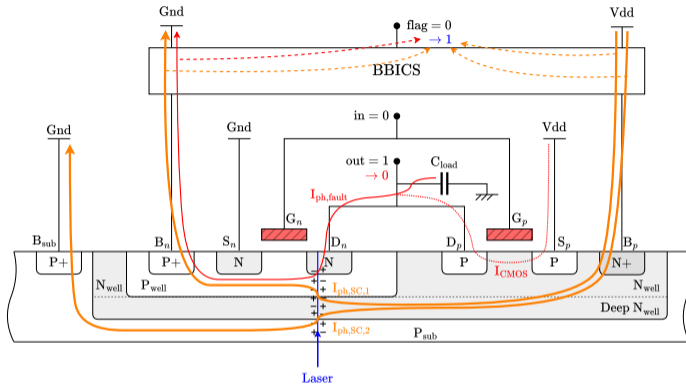
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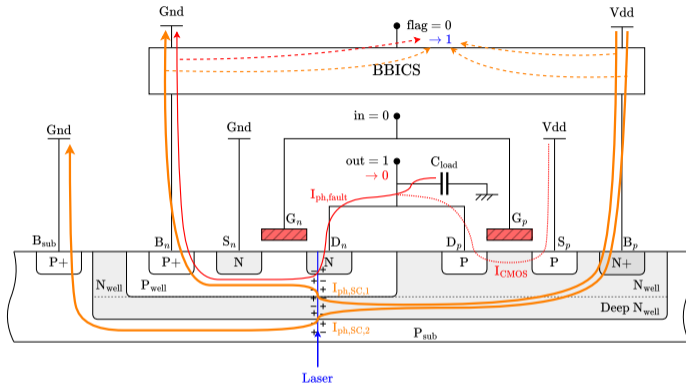


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Triple-Well Logic Target  $\Rightarrow I_{SC,1}$  AND  $I_{SC,2}$   
 $\Rightarrow$  Improved (simulated) sensitivity [1]

# MODELING

## Accurate modeling is complex:

- › Photocurrent generation
- › Propagation of photocurrents to the sensor (through bulk)
  - › Bulk electrical properties (filtering)
  - › Multiple “concurrent” biasing contacts (current divider)
- › Other Effects
  - › Parasitic bipolar effects (due to bulk potential disruption)
  - › IR drop (due to intensive current calls)

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**We NEED experimental results !**

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Reference	Champeix <i>et al.</i> [1]	Borrel <i>et al.</i> [2]	Matsuda <i>et al.</i> [3]
Technology	90 nm	90 nm	180 nm
Target	Dual-Well logic	Dual-Well logic Triple-Well logic	Dual-Well AES core
Laser pulse duration	200-50 ns	long $\mu$ s to short ns	60 ns

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Technology	90 nm	90 nm	180 nm	<b>65 nm</b>
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Laser pulse duration	200-50 ns	long $\mu$ s to short ns	60 ns	50 ns and <b>30 ps</b>

## Our Contributions:

- › Testing for a 65 nm CMOS technology target
- › Extend results to picosecond-range pulse testing for standard-cell targets
- › Provide additional results on Triple-Well monitoring

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- › Ensure (at fault threshold) :

**Target area  $\subset$  BBICS detection area**

# SETUP

## Backside LFI:

- › 120  $\mu\text{m}$  substrate thinning

## Laser pulses:

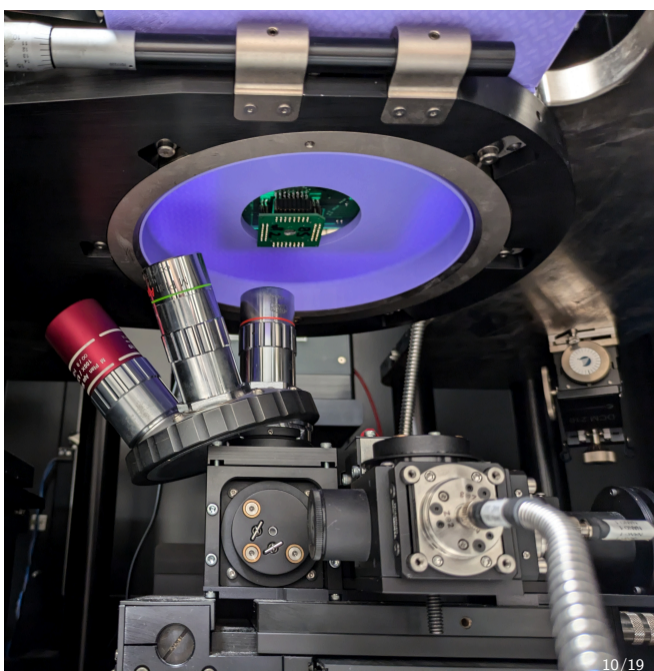
- › 50 ns ( $\lambda = 1,064$  nm)
- › 30 ps ( $\lambda = 1,030$  nm)

## Spot diameters:

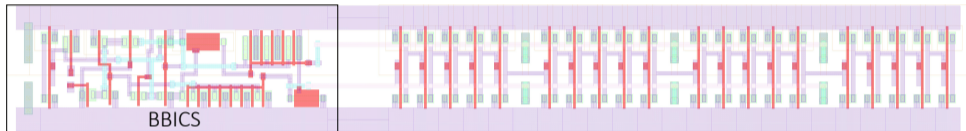
- › 5  $\mu\text{m}$  ( $\times 20$  magnification)
- › 1  $\mu\text{m}$  ( $\times 100$  magnification)

## Two test structures...

- › 65 nm CMOS technology



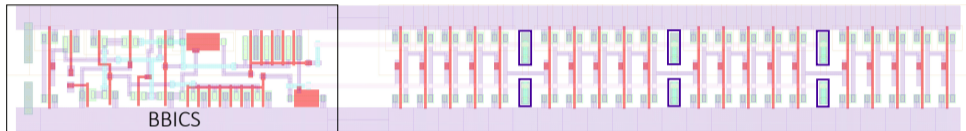
# DUAL-WELL TEST STRUCTURE



Dual-Well BBICS monitoring a chain of 20 Dual-Well inverters (6 biasing contacts):

- › Sensor area :  $22 \mu m^2$
- › Target area :  $40 \mu m^2$

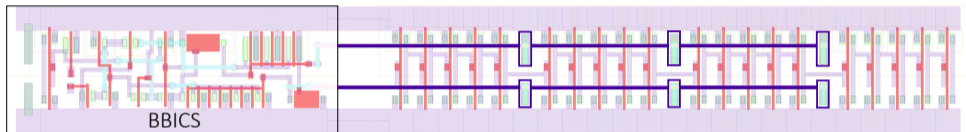
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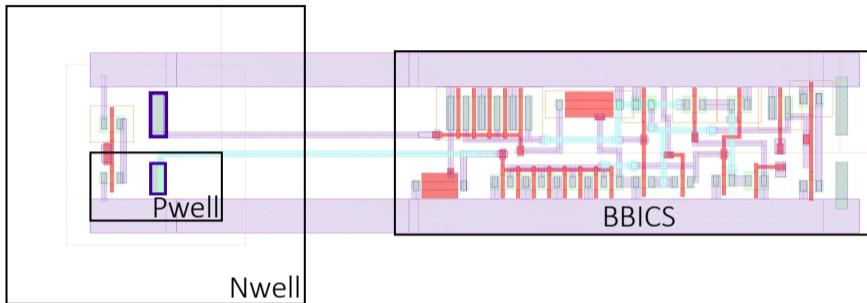


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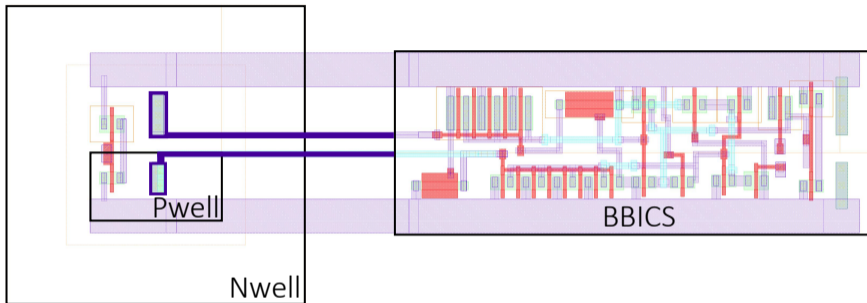
# TRIPLE-WELL TEST STRUCTURE



Dual-Well BBICS monitoring a single Triple-Well inverter (2 biasing contact):

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# FAULT THRESHOLDS

Dual-Well fault thresholds (empirical)

Cell	DFF				buffer			
	50ns		30ps		50ns		30ps	
Pulse duration	50ns		30ps		50ns		30ps	
Spot diameter	5 $\mu\text{m}$	1 $\mu\text{m}$	5 $\mu\text{m}$	1 $\mu\text{m}$	5 $\mu\text{m}$	1 $\mu\text{m}$	5 $\mu\text{m}$	1 $\mu\text{m}$
Fault threshold	1.9 W	1.7 W	5 nJ	2 nJ	2.1 W	-	5 nJ	3 nJ

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**0.85 W**

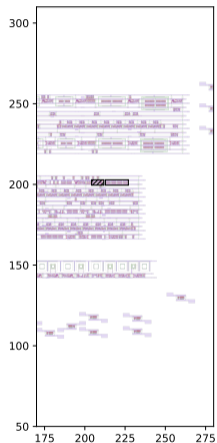
  
**1 nJ**

Triple-Well fault threshold  $\simeq \frac{\text{Dual-Well fault threshold}}{2}$   
(Borrel *et al.*)

# Dual-Well Test Structure : 50 ns pulse, 5 $\mu\text{m}$ spot

Y position ( $\mu\text{m}$ )  
X position ( $\mu\text{m}$ )

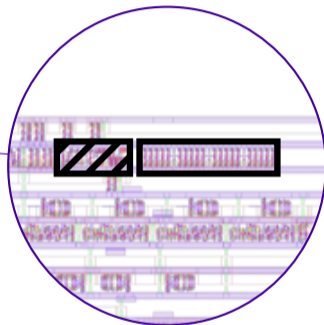
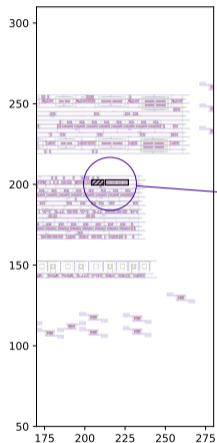
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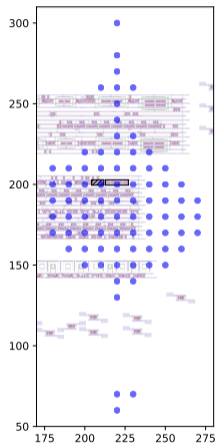
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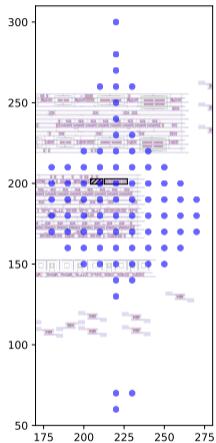
(a) Power = 1.7 W

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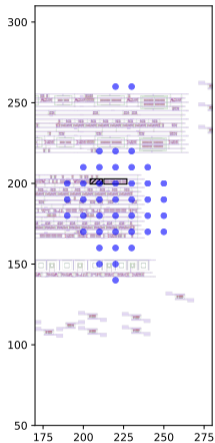
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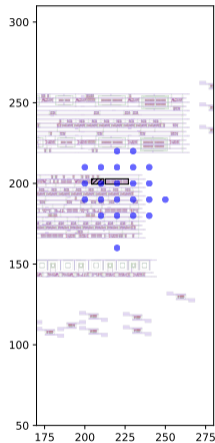
Target BBICS Detection



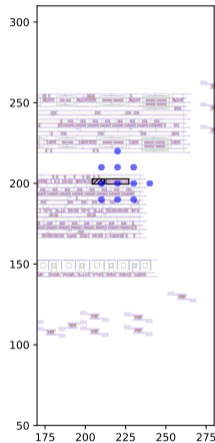
(a) Power = 1.7 W



(b) Power = 0.7 W



(c) Power = 0.3 W

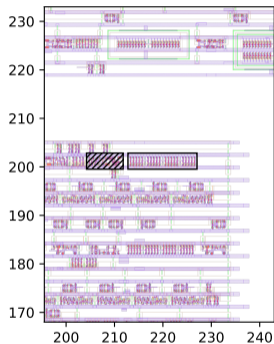


(d) Power = 0.1 W

# Dual-Well Test Structure : 30 ps pulse, 1 $\mu\text{m}$ spot

Y position ( $\mu\text{m}$ )  
X position ( $\mu\text{m}$ )

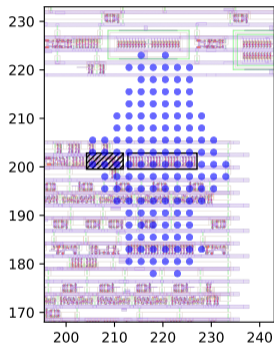
Target BBICS Detection



# Dual-Well Test Structure : 30 ps pulse, 1 $\mu\text{m}$ spot

Y position ( $\mu\text{m}$ )  
X position ( $\mu\text{m}$ )

Target BBICS Detection

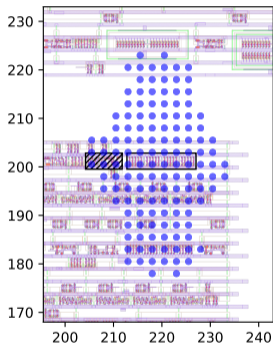


(a) Energy = 2 nJ

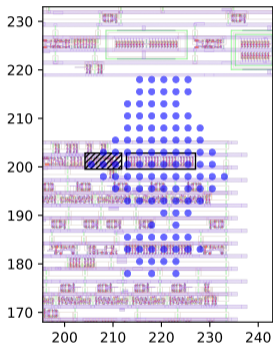
# Dual-Well Test Structure : 30 ps pulse, 1 $\mu\text{m}$ spot

Y position ( $\mu\text{m}$ )  
X position ( $\mu\text{m}$ )

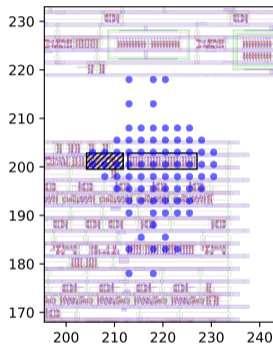
Target BBICS Detection



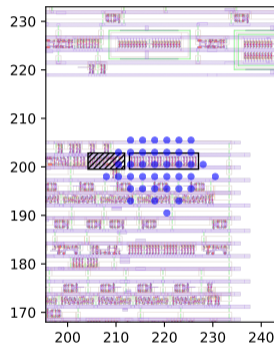
(a) Energy = 2 nJ



(b) Energy = 1.5 nJ

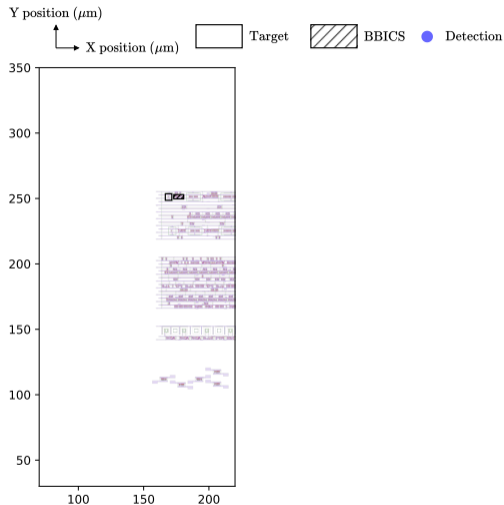


(c) Energy = 1 nJ

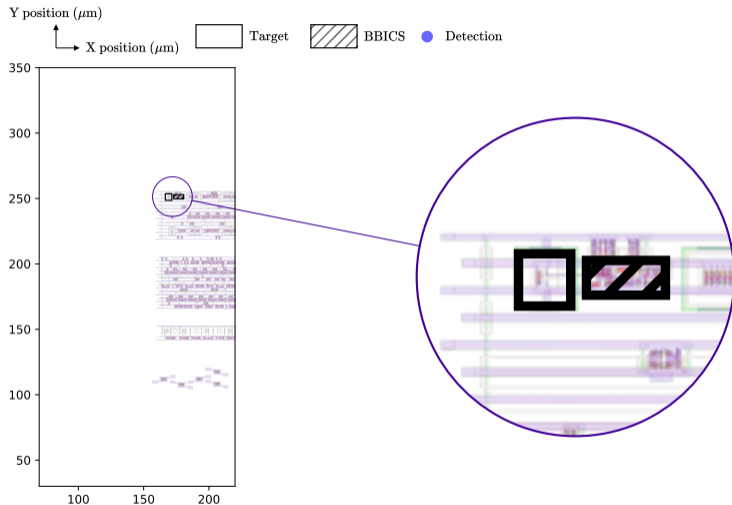


(d) Energy = 0.5 nJ

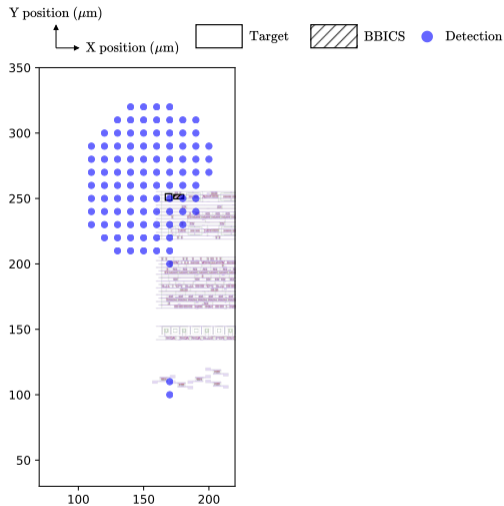
# Triple-Well Test Structure : 50 ns pulse, 5 $\mu\text{m}$ spot



# Triple-Well Test Structure : 50 ns pulse, 5 $\mu\text{m}$ spot

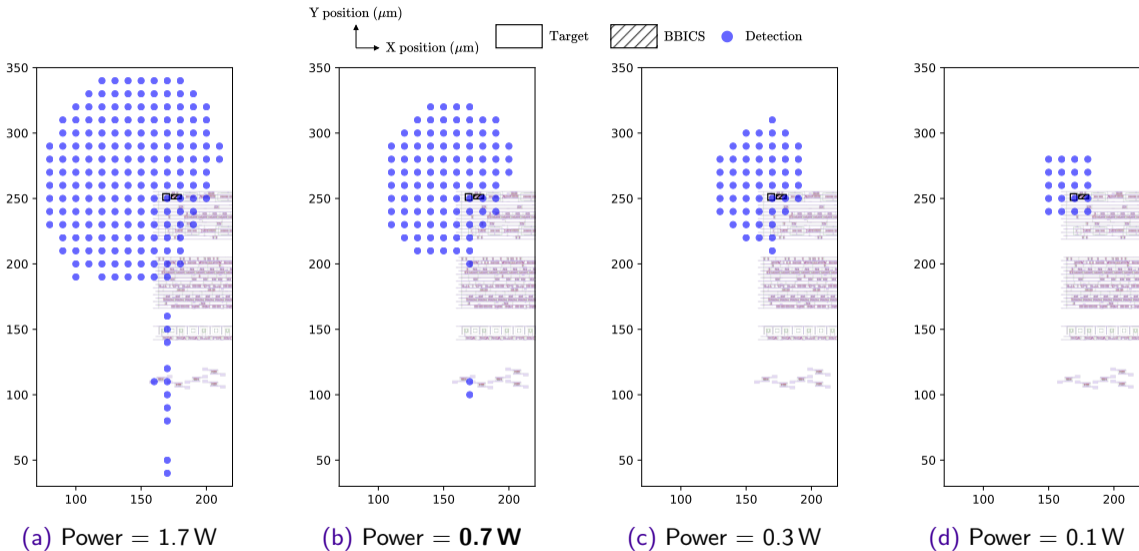


# Triple-Well Test Structure : 50 ns pulse, 5 $\mu\text{m}$ spot



(b) Power = **0.7 W**

# Triple-Well Test Structure : 50 ns pulse, 5 $\mu\text{m}$ spot



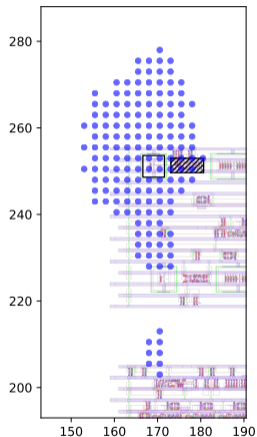




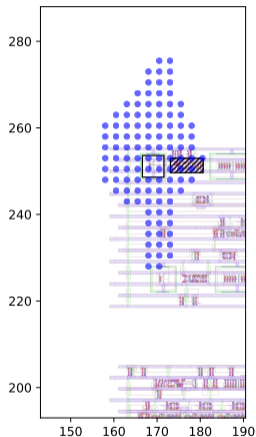
# Triple-Well Test Structure : 30 ps pulse, 1 $\mu\text{m}$ spot

Y position ( $\mu\text{m}$ )  
X position ( $\mu\text{m}$ )

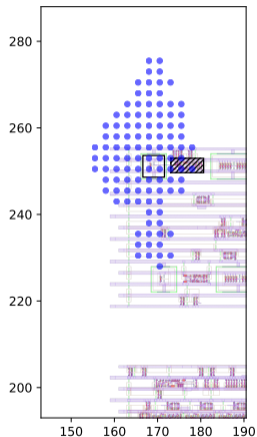
Target BBICS Detection



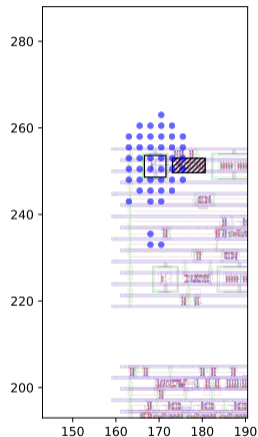
(a) Energy = 2 nJ



(b) Energy = 1.5 nJ



(c) Energy = 1 nJ



(d) Energy = 0.5 nJ

# SYNTHESIS

Sensor area	22 $\mu\text{m}^2$			
Test structure	Dual-Well		Triple-Well	
Target area	40 $\mu\text{m}^2$		25 $\mu\text{m}^2$	
Pulse duration	50 ns	30 ps	50 ns	30 ps
Spot diameter	5 $\mu\text{m}$	1 $\mu\text{m}$	5 $\mu\text{m}$	1 $\mu\text{m}$
Detection area at fault threshold	7,000 $\mu\text{m}^2$	819 $\mu\text{m}^2$	9,500 $\mu\text{m}^2$	638 $\mu\text{m}^2$

For every tested parameters:  
**Target area  $\subset$  BBICS Detection area**

The BBICS efficiently monitors Triple-Well CMOS logic and Picosecond LFI !

# OUTLINE

- › BBICS Principle
- › BBICS Experimental State-of-the-Art
- › Experimental Methodology & Setup
- › Experimental Assessment
- › Conclusion

## Experimental assessment of BBICS LFI monitoring capabilities was provided

Reference	Champeix <i>et al.</i>	Borrel <i>et al.</i>	Matsuda <i>et al.</i>	<b>This Work</b>
Technology	90 nm	90 nm	180 nm	<b>65 nm</b>
Target	Dual-Well logic	Dual-Well logic Triple-Well logic	Dual-Well AES core	Dual-Well logic Triple-Well logic
Laser pulse duration	200-50 ns	long $\mu$ s to short ns	60 ns	50 ns and <b>30 ps</b>

Study of **BBICS detection area** at parameters associated to logic **fault threshold...**

- › **Confirmed** BBICS efficiency in monitoring...
  - › 65 nm Dual-Well logic against nanosecond-range pulses
- › **Ascertained** BBICS efficiency in monitoring...
  - › 65 nm Dual-Well logic against picosecond-range pulses
  - › 65 nm Triple-Well logic against nanosecond-range pulses
  - › 65 nm Triple-Well logic against picosecond-range pulses

## Experimental assessment of BBICS LFI monitoring capabilities was provided

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Leverage experimental data for integration ?

## CONTACT

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IDEMIA StarChip

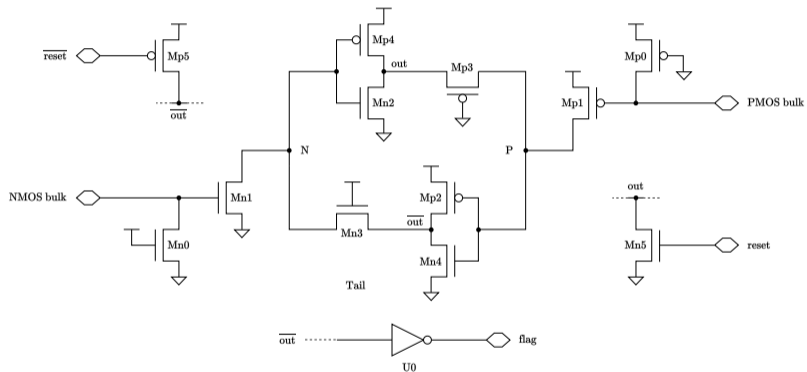
[axel.guichaoua@idemia.com](mailto:axel.guichaoua@idemia.com)



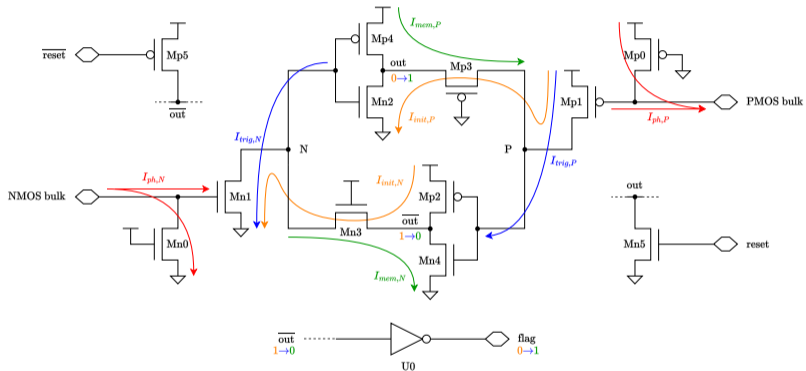
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# APPENDIX



# APPENDIX



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